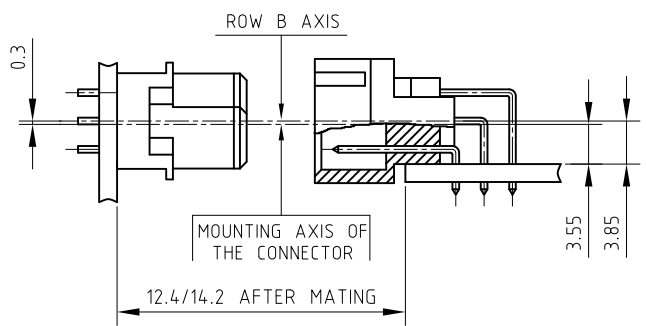
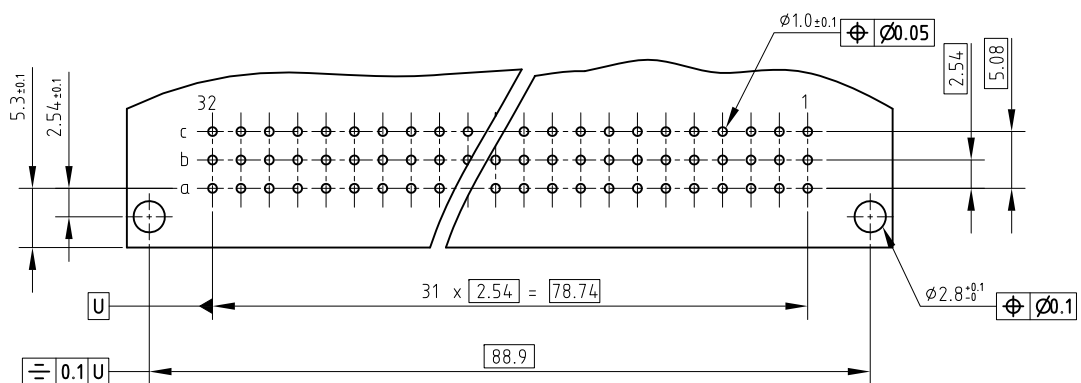


PCB DRILLING DETAILS



TECHNICAL SPECIFICATION

HOUSING MATERIAL : THERMOPLASTIC POLYESTER UL94V0; GREY
 HOUSING CAN WITHSTAND EXPOSURE TO LEAD FREE WAVE SOLDERING TEMPERATURE OF 260-265°C
 WHEN USED WITH PROTECTIVE ADHESIVE OR PROTECTIVE METALLIC DEVICE FOR ANGLE CONNECTORS AS IT IS USED IN CLASSICAL LEAD WAVE SOLDERING AT 235-250°C.
 CONTACT & HARPOON MATERIAL : COPPER ALLOY
 CONTACT PLATING :
 CONTACT ZONE : Au OVER Ni (or) Au+Pd-Ni OVER Ni
 TERMINATION ZONE : Sn (PURE MATT) OVER Ni FOR LEAD FREE VERSION
 HARPOON PLATING : Sn (PURE MATT) OVER Ni FOR LEAD FREE VERSION

ELECTRICAL DATA

CURRENT RATING AT 20°C : 1.5 A
 CURRENT (I MAX) : 2 A
 TEMPERATURE RANGE : -55°C TO +125°C
 CONTACT RESISTANCE : ≤ 20mΩ
 INSULATION RESISTANCE : ≥ 10⁶ MΩ
 TEST VOLTAGE (rms) : 1000 V

MECHANICAL DATA

INSERTION FORCE PER CONTACT : ≤ 0.94 N
 EXTRACTION FORCE PER CONTACT : ≥ 0.15 N

REFERENCE SPECIFICATION : DIN 41612 / IEC 603-2

SERIES	8609	3	64	7	1	13	7	6	0	SKLF
ROWS FITTED WITH CONTACTS										
ROW a b c	3 64									
NO. OF CONTACTS										
TYPE OF INSULATOR										
3 ROW MALE INSULATOR	7									
METHOD OF MOUNTING										
STANDARD MOUNTING - STYLE C	1									
TERMINATION										
ANGLED SPILL	13									
OPTIONS										
NO OPTION	7									
WITH HARPOONS	H									
PERFORMANCE CLASS										
DIN 41612 CLASS 3	4									
DIN 41612 CLASS 2	5									
DIN 41612 CLASS 1	6									
AS PER MIL C 55302 / JSS 50808	8									
PITCH PER ROW										
MIXED PITCH	0									
SPECIAL CODE: SPECIAL LOADING OF CONTACTS, LEAD FREE VERSION	SKLF									
CONTACTS LOADED ONLY IN	a: 1,2,3,4,5,6,7,8,9,10,11,12,13,14,15,16,17,18,19,20,21,22,23,24,25,26,27,28,29,30,31,32 b: 2,4,6,8,10,12,14,16,18,20,22,24,26,28,30,32 c: 2,4,6,8,10,12,14,16,18,20,22,24,26,28,30,32									

NOTES:
 1. THE "LF" PRODUCTS MEET EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008.
 2. THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C PEAK TEMPERATURE FOR 3.5 SECONDS IN A WAVE SOLDER APPLICATION WITH A 1.6 MM MINIMUM THICK CIRCUIT BOARD.
 3. LEAD FREE OR RoHS DIRECTIVE LABELING TO BE PROVIDED AS PER GS-14-920 FOR LEAD FREE VERSION.

mat'l. code SEE TECH. SPEC.				surface ISO 1302 ✓ ISO 406 ISO 1101		tolerance tolerances unless otherwise specified		projection mm		product family 8609			
A I10-0164 SAL 2010-08-16				B ELX-I-25006 MJA 2016-09-22		.0±.1		mm		title DIN STANDARD HEADER ANGLED SPILL DIN 41612 STYLE-C			
dr JOHN SLEEBA 2008-09-05				enr JOHN SLEEBA 2008-09-05		0°±1°		scale 3:2		dwg no C-8609-2149		sheet 1 of 1 size A3	
chr M JACOB 2016-09-22				appd BIJU K PAUL 2016-09-22				Amphenol FCi		type Product Customer Drawing			
sheet index		revision sheet		B 1									